TOSHIBA 2SK3067

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $\pi$ -MOSV)

# 2 S K 3 O 6 7

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

Low Drain-Source ON Resistance :  $R_{DS(ON)} = 4.2 \Omega$  (Typ.)

High Forward Transfer Admittance :  $|Y_{fs}| = 1.7 \,\mathrm{S}$  (Typ.)

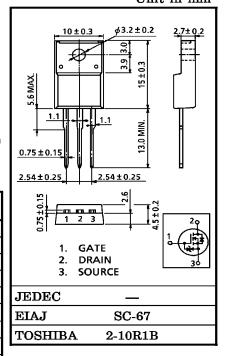
Low Leakage Current :  $I_{DSS} = 100 \,\mu\text{A}$  (Max.) ( $V_{DS} = 600 \,\text{V}$ )

Enhancement-Mode :  $V_{th} = 2.0 \sim 4.0 \text{ V} \text{ (V}_{DS} = 10 \text{ V}, I_D = 1 \text{ mA)}$ 

## MAXIMUM RATINGS (Ta = 25°C)

CHARAC	SYMBOL	RATING	UNIT	
Drain-Source Volt	$v_{ m DSS}$	600	V	
Drain-Gate Voltag	$v_{ m DGR}$	600	V	
Gate-Source Volta	$v_{GSS}$	±30	V	
Drain Current	DC	$I_{\mathbf{D}}$	2	Α
	Pulse (t = 1 ms)	${ m I_{DP}}$	5	Α
	Pulse (t = $100 \mu s$ )	$I_{ m DP}$	8	Α
Drain Power Diss	$P_{\mathrm{D}}$	25	w	
Single Pulse Aval	EAS	93	mJ	
Avalanche Currer	$^{ m I}{ m AR}$	2	A	
Repetitive Avalan	$\mathbf{E_{AR}}$	2.5	mJ	
Channel Tempera	$\mathrm{T_{ch}}$	150	$^{\circ}\mathrm{C}$	
Storage Temperat	$\mathbf{T_{stg}}$	-55~150	°C	

## INDUSTRIAL APPLICATIONS Unit in mm



## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	Rth (ch-c)	5.0	°C/W
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

#### Note;

- \* Repetitive rating; Pulse Width Limited by Max. junction temperature.
- \*\*  $V_{DD} = 90 \text{ V}, T_{ch} = 25^{\circ}\text{C}$  (initial),  $L = 41 \text{ mH}, R_G = 25 \Omega, I_{AR} = 2 \text{ A}$

This transistor is an electrostatic sensitive device. Please handle with caution.

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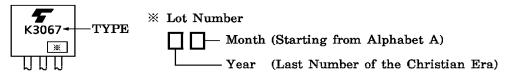
# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARAC	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	Current	$I_{GSS}$	$V_{GS} = \pm 25 V, V_{DS} = 0 V$			±10	$\mu$ A
Gate-Source I Voltage	Breakdown	V <sub>(BR)</sub> GSS	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	v
Drain Cut-off	Current	IDSS	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	$\mu$ A
Drain-Source Voltage	Breakdown		$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	_	_	v
Gate Thresho	ld Voltage	$v_{ m th}$	$V_{\mathrm{DS}} = 10  \mathrm{V}, \; \mathrm{I_D} = 1  \mathrm{mA}$	2.0	_	4.0	v
Drain-Source	ON Resistance	R <sub>DS</sub> (ON)	$V_{GS} = 10 V$ , $I_D = 1 A$	_	4.2	5.0	Ω
Forward Tran Admittance	sfer	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ A}$	0.8	1.7	_	S
Input Capacitance		$\mathrm{C_{iss}}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	_	380	_	pF
Reverse Transfer Capacitance		$C_{rss}$		_	40	_	
Output Capac	Output Capacitance		1 — 1 MIIIZ	_	120	_	
Switching Time	Rise Time	t <sub>r</sub>	$V_{GS} = \begin{bmatrix} 10 \text{ V} & I_D = 1 \text{ A} \\ 0 \text{ V} & R_L = \\ 200 \Omega \end{bmatrix}$ $V_{IN} : t_r, t_f < 5 \text{ ns}, V_{DD} = 200 \text{ V}$ $Duty \leq 1\%, t_w = 10 \mu\text{s}$	_	15	_	
	Turn-on Time	t <sub>on</sub>		_	25	_	ns
	Fall Time	ь			20		113
	Turn-off Time	t <sub>off</sub>		_	80	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$Q_{\mathrm{g}}$	$V_{DD} = 480 \text{ V}, V_{GS} = 10 \text{ V},$		9		" <sub>C</sub>
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{\mathbf{D}} = 2 \text{ A}$	_	5		nC
Gate-Drain ("Miller") Charge		$Q_{ m gd}$			4		

# SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	${ m I}_{ m DR}$	-	_	_	2	A
Pulse Drain Reverse Current	${ m I}_{ m DRP}$	t = 1  ms		_	5	A
	${ m I}_{ m DRP}$	$t = 100 \mu s$	1	_	8	A
Diode Forward Voltage	${ m v_{DSF}}$	$I_{DR} = 2 A$ , $V_{GS} = 0 V$	_	_	-1.5	V
Reverse Recovery Time	$\mathbf{t_{rr}}$	$I_{DR} = 2 A$ , $V_{GS} = 0 V$		1000	_	ns
Reverse Recovery Charge	${f Q_{rr}}$	$dI_{DR}/dt = 100  A/\mu s$	_	5.0	_	μC

# **MARKING**



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